



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

#19/D  
2/4/03  
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In re the Application of: **TAKADA, Kazuhiko**

GROUP 1, Int. Cl. 2800

Serial No.: **09/528,296**

Examiner: **NADAV, Ori**

Filed: **March 17, 2000**

FOR: **SEMICONDUCTOR DEVICE HAVING A GUARD RING**

**PRELIMINARY AMENDMENT**

Commissioner for Patents  
Washington, D.C. 20231

Date: January 30, 2003

Sir:

Please amend as follows:

**IN THE CLAIMS:**

Cancel claim 5 without prejudice or disclaimer.

Amend the claim 1 as follows:

sub E1  
D1

1. (Four Times Amended) A semiconductor device, comprising:  
a substrate; and  
a multilayer interconnection structure formed on said substrate,  
said multilayer interconnection structure including: at least first and second interlayer  
insulation films provided on said substrate; and a guard ring pattern embedded in each of said first  
and second interlayer insulation films, said guard ring pattern extending along a periphery of said  
substrate, said multilayer interconnection structure being planarized by using a CMP process,